Wafer Packaging check list

Applicant		
Applicant	**COMPANY**	
	NAME	
	EMAIL	
	Cellular phone	

Items	Check list	Value
Wafer	1. Size (diameter)	_______________ (mm)
	2. Incoming thickness	_______________ (um)
	3. Die quantity	_________________ 개
Die	1. Die Size (width x length)	________x _______ (um)
	2. PAD Size (width x length)	________x _______ (um)
	3. PAD quantity	_____ , _____ , _____ , _____ , Left, right, top, bottom
	4. Center distance between nearest PADs	________________ (um)
	5. Die PAD shape (inline & staggered)	
	6. Die layout image	Please send to "kiapek@mtechpcb.co.kr"
Package	1. Package Type	
	2. Package Size (width x length)	________x _______(mm)
	3. BGA Ball quantity	
	4. BGA Piatch & Ball Size	* Pitch : _____(mm) * Size : _____(mm)
	5. Solder Ball Material	
ETC	1. Substrate Layer, Thickness	* Layer : _____* Thickness : _____(mm)
	2. Die PAD List & Ball Map	
	3. Bonding Wire Material, Thickness	* Material : ____ * Thickness : ____(mm)
	4. Bonding Wire Expected quantity	______________EA
	5. Socket manufacturing quantity (Socket for connection between evaluation board and chip)	______________ EA
	6. Back grinding, Sawing	* Grinding : ☐ * Sawing : ☐
	7. Laser marking	
	8. Marking for die location on wafer	* marking : ☐